



Special Issue on Thin Film Materials and Its Applications

Call for Papers

Thin films are important because they offer the potential for low-cost processing with minimal material usage while fulfilling application requirements. Importantly, this can enable cost-effective applications for expensive raw source materials. Thin films also can enable applications where low weight and mechanical flexibility are crucial. The goal of this special issue is to provide a platform for scientists and academicians all over the world to promote, share, and discuss various new issues and developments in the area of **thin film materials and its applications**.

In this special issue, we intend to invite front-line researchers and authors to submit original research and review articles on exploring **thin film materials and its applications**. Potential topics include, but are not limited to:

- Film deposition methods
- Modes of film growth by vapor deposition
- Film microstructures
- Processing of microelectronic structures
- Film stress and substrate curvature
- Thin Film materials and devices
- Thin Film Processes

Authors should read over the journal's [For Authors](#) carefully before submission. Prospective authors should submit an electronic copy of their complete manuscript through the journal's [Paper Submission System](#).

Please kindly specify the “**Special Issue**” under your manuscript title. The research field “**Special Issue - Thin Film Materials and Its Applications**” should be selected during your submission.

Special Issue Timetable:

Submission Deadline	November 18th, 2020
Publication Date	January 2021

Guest Editor:

For further questions or inquiries,
please contact Editorial Assistant at
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